



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

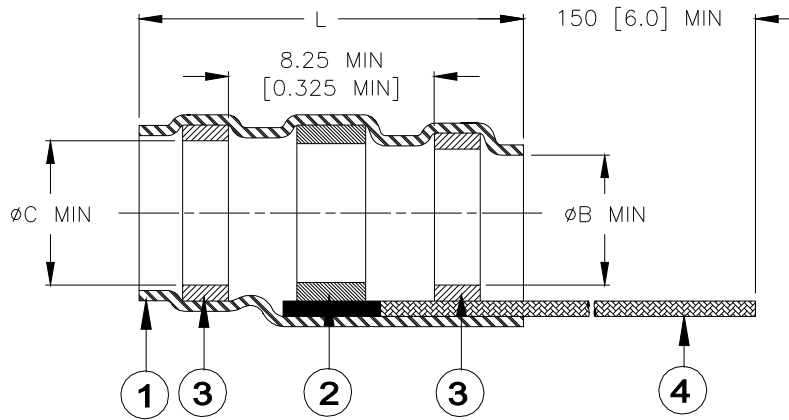
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SPECIFICATION CONTROL DRAWING



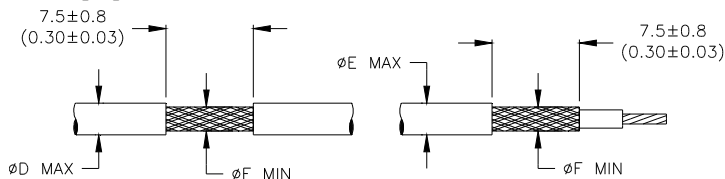
Product Revision		Ident. Code	Component Dimensions			Shall Accommodate with Cable Dimensions		
Product Name			$L \pm 1.75$ ($L \pm 0.070$)	ϕB min	ϕC min	ϕD max	ϕE max	ϕF min
SO63-1-01	E	SO631R	16.50 (0.650)	1.90 (0.075)	2.65 (0.105)	1.90 (0.075)	2.65 (0.105)	0.90 (0.035)
SO63-2-01	E	SO632R	16.50 (0.650)	2.65 (0.105)	3.68 (0.145)	2.65 (0.105)	3.68 (0.145)	1.40 (0.055)
SO63-3-01	E	SO633R	16.50 (0.650)	4.30 (0.170)	5.08 (0.200)	4.30 (0.170)	5.08 (0.200)	2.15 (0.085)
SO63-4-01	E	SO634R	19.10 (0.750)	5.95 (0.235)	6.45 (0.255)	5.95 (0.235)	6.45 (0.255)	3.30 (0.130)
SO63-5-01	E	SO635R	19.10 (0.750)	7.00 (0.275)	7.60 (0.300)	7.00 (0.275)	7.60 (0.300)	4.30 (0.170)

MATERIALS

- INSULATION SLEEVE: Heat-shrinkable, transparent blue, radiation cross-linked modified polyvinylidene fluoride.
- SOLDER PREFORM WITH FLUX AND THERMAL INDICATOR:
 SOLDER: TYPE Sn63 per ANSI/J-STD-006.
 FLUX: TYPE ROL1 per ANSI/J-STD-004.
 THERMAL INDICATOR: Fusible ring, melt point: 221°C.
- MELTABLE RINGS: Stabilized thermoplastic. Color: blue.
- PRE-INSTALLED BRAID: Nickel-plated copper strands. CMA 640.

APPLICATION

- These parts are designed to provide an environment protected shield termination on cables, rated for 125°C minimum, meeting the dimensional criteria listed and having tin or silver-plated shields and insulation compatible with the insert material.
For compatible insulations, see MIL-S-83519/2 or consult TE Connectivity/Raychem.
- When installed per Raychem process standard RCPS-100-70, assemblies will meet those requirements of Raychem Specification RT-1404 and MIL-S-83519/2 which do not require electrical testing while parts are immersed in water.
- Temperature range: -55°C to +150°C.
- Parts shall be marked with identification code per table.
For best results, prepare the cable as shown:



		TE Connectivity 300 Constitution Drive, Menlo Park, CA. 94025, U.S.A.				TITLE: SOLDERSLEEVE DEVICE SHIELD TERMINATION WITH BRAID									
Unless otherwise specified dimensions are in millimeters. [Inches dimensions are shown in brackets]				DOCUMENT NO.: SO63-XX-01											
TOLERANCES: 0.00 N/A 0.0 N/A 0 N/A		ANGLES: N/A ROUGHNESS IN MICRON		TE Connectivity reserves the right to amend this drawing at any time. Users should evaluate the suitability of the product for their application.		DOC. ISSUE: 6		DATE: 15-Apr-11							
DRAWN BY: M. FORONDA		CAGE CODE: 06090		REPLACES: D982100		DCR NUMBER: D030398		PROD. REV.: SEE TABLE		SCALE: None		SIZE: A		SHEET: 1 of 1	